

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

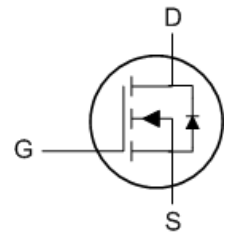
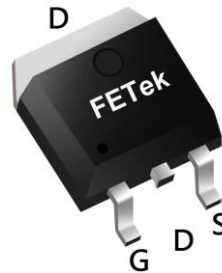
**Product Summary**


BVDSS	RDSON	ID
80V	6.5mΩ	108A

**Description**

The FKH8024A is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FKH8024A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**TO263 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	108	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	68	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	200	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	125	mJ
$I_{AS}$	Avalanche Current	50	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	149	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	55	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.84	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	80	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=54A$	---	---	6.5	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2.5	---	4.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=64V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=64V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=30A$	---	50	---	S
$Q_g$	Total Gate Charge (10V)	$V_{DS}=64V, V_{GS}=10V, I_D=30A$	---	83.7	---	nC
$Q_{gs}$	Gate-Source Charge		---	28.6	---	
$Q_{gd}$	Gate-Drain Charge		---	29.3	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=40V, V_{GS}=10V, R_G=3.3\Omega, I_D=30A$	---	38.1	---	ns
$T_r$	Rise Time		---	73.3	---	
$T_{d(off)}$	Turn-Off Delay Time		---	51.6	---	
$T_f$	Fall Time		---	26.1	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	5580	---	pF
$C_{oss}$	Output Capacitance		---	571	---	
$C_{rss}$	Reverse Transfer Capacitance		---	278	---	

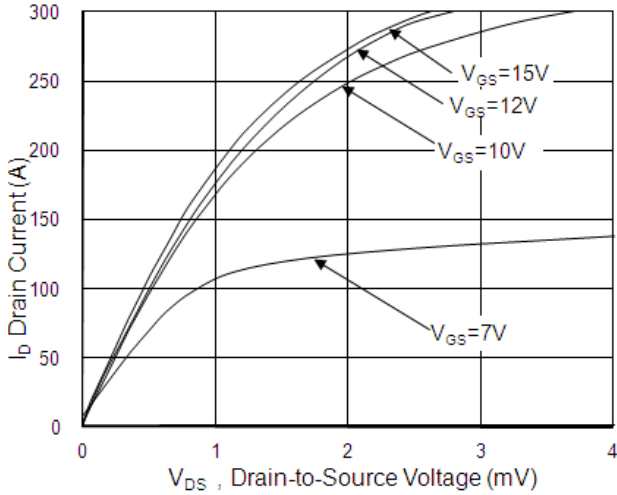
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	70	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=A, T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=30A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	26.7	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	27.9	---	nC

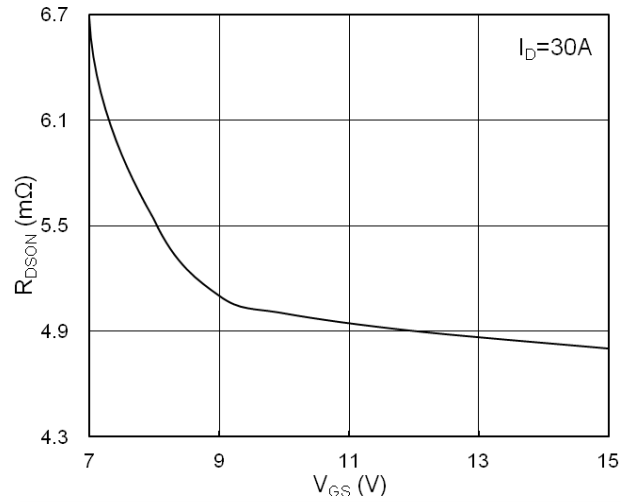
Note :

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=50A$
- The power dissipation is limited by 150 $^\circ\text{C}$  junction temperature
- The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.
- Package limitation current is 70A.

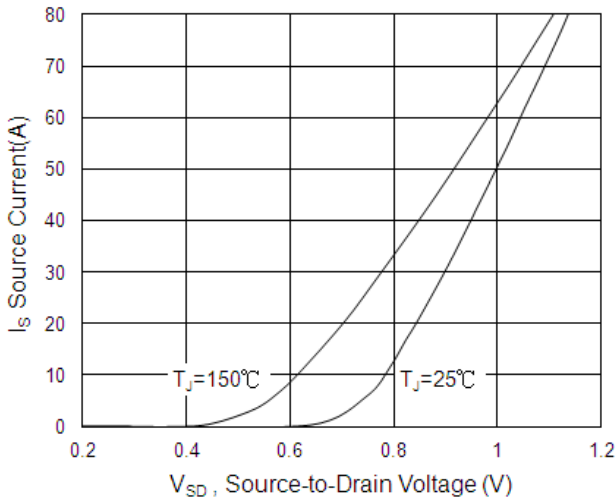
**Typical Characteristics**



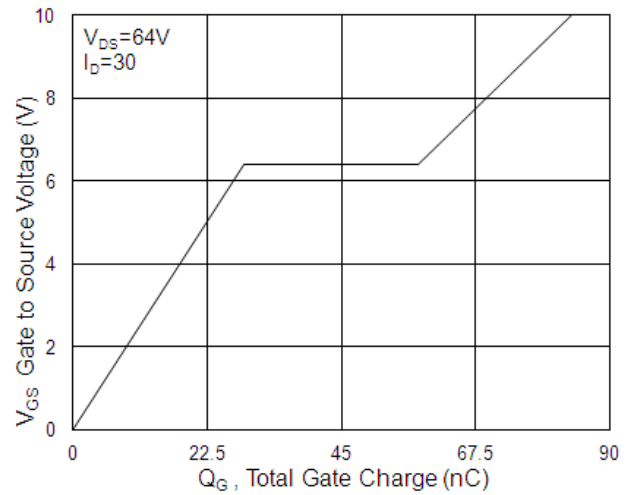
**Fig.1 Typical Output Characteristics**



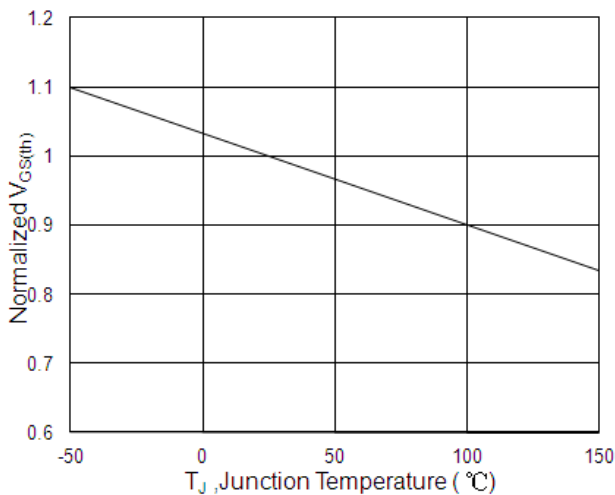
**Fig.2 On-Resistance vs. G-S Voltage**



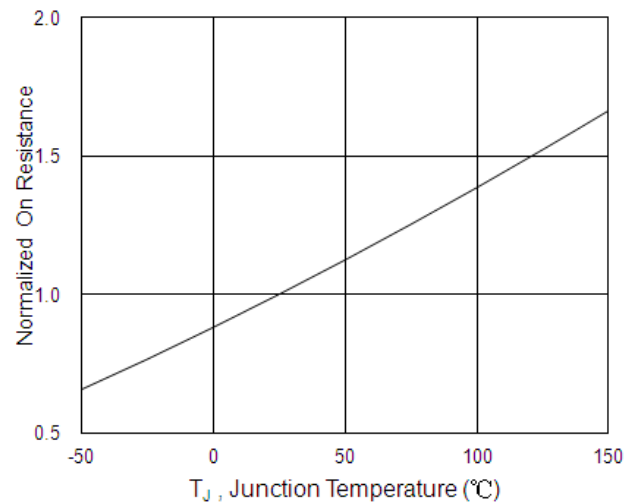
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

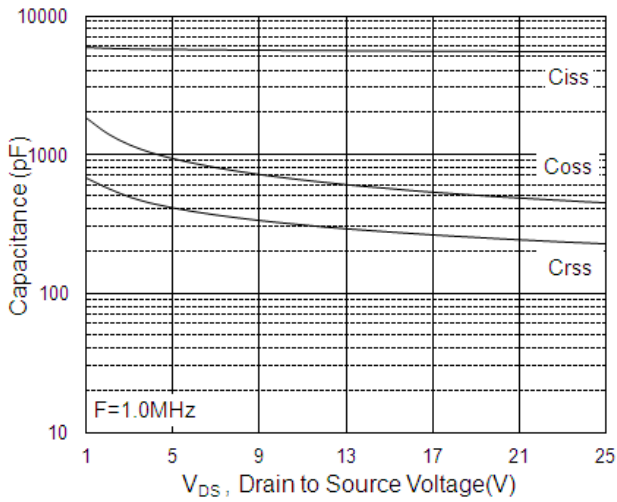


Fig.7 Capacitance

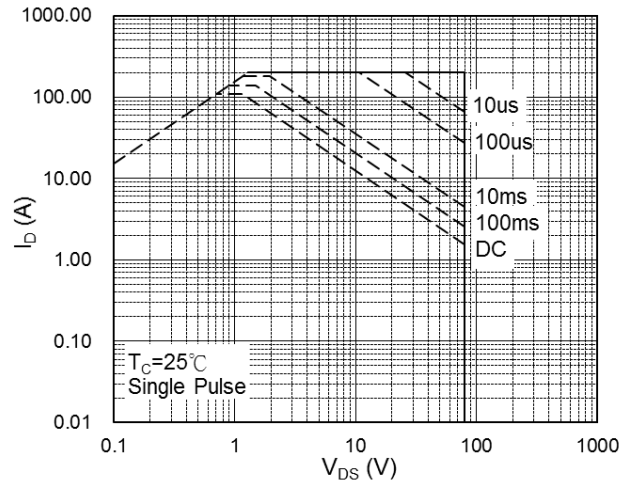


Fig.8 Safe Operating Area

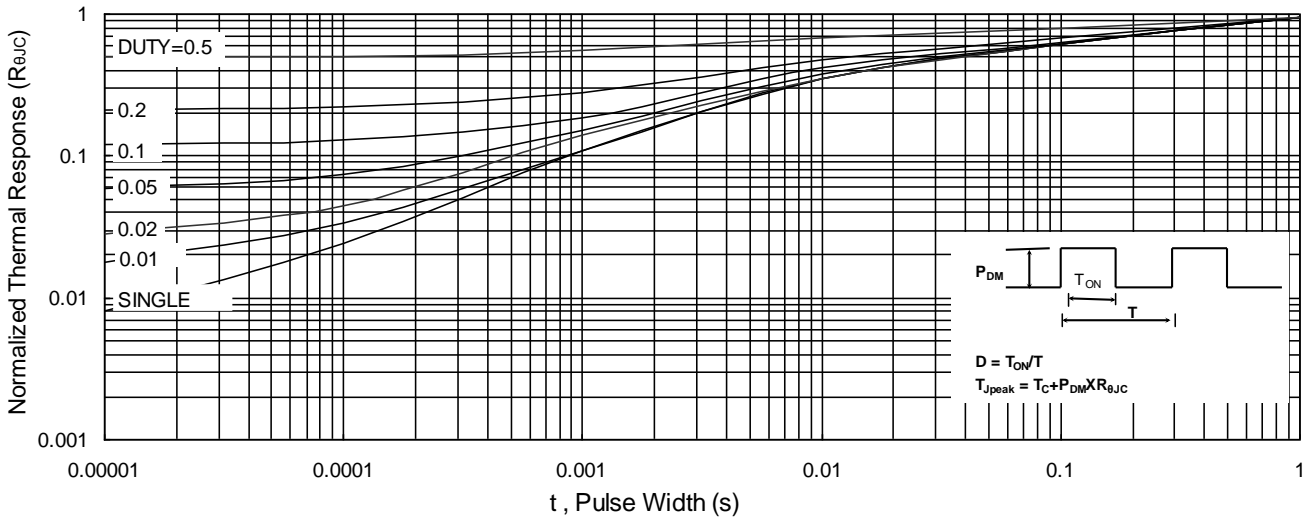


Fig.9 Normalized Maximum Transient Thermal Impedance

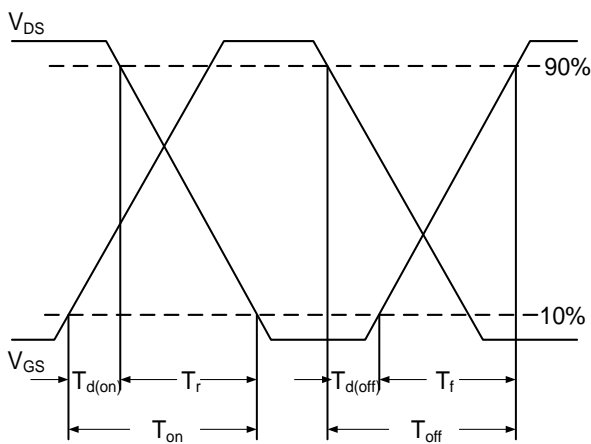


Fig.10 Switching Time Waveform

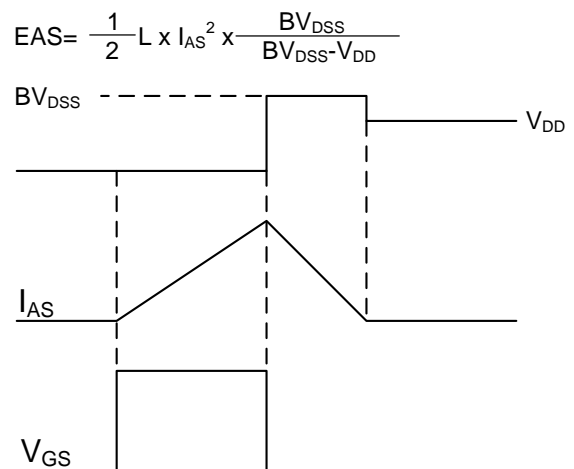
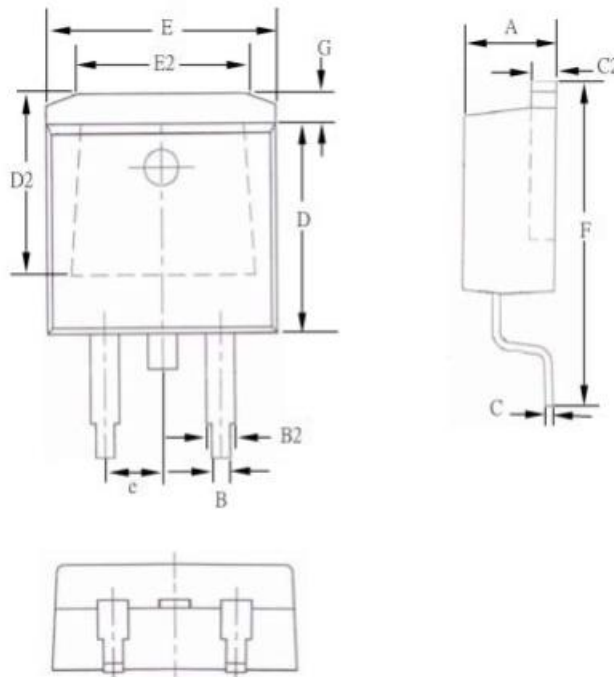


Fig.11 Unclamped Inductive Switching Waveform

## TO263 Package Outline Dimensions



SYMBOL	MILLIMETERS			INCHES		
	MIN	NOM		MIN	NOM	
A	4.06	—	4.83	0.160	—	0.190
B	0.51	—	0.99	0.020	—	0.039
B2	1.14	—	1.78	0.045	—	0.070
C	0.34	—	0.74	0.013	—	0.029
C2	1.14	—	1.65	0.045	—	0.065
D	8.38	—	9.65	0.330	—	0.380
D2	6.86	—	7.86	0.270	—	0.309
E	9.65	—	10.67	0.380	—	0.420
E2	6.22	—	7.40	0.245	—	0.291
F	13.08	—	15.50	0.515	—	0.610
G	0.68	—	1.68	0.027	—	0.066
e	—	2.54	—	—	0.100	—